

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

| Characteristic                     | Symbol                   | Value | Unit | Conditions             |
|------------------------------------|--------------------------|-------|------|------------------------|
| Peak Pulse Power Dissipation       | P <sub>PP</sub>          | 84    | W    | 8/20μs, Per Fig. 2     |
| Peak Pulse Current                 | I <sub>PP</sub>          | 6     | A    | 8/20μs, Per Fig. 2     |
| ESD Protection – Contact Discharge | V <sub>ESD_Contact</sub> | ±30   | kV   | Standard IEC 61000-4-2 |
| ESD Protection – Air Discharge     | V <sub>ESD_Air</sub>     | ±30   | kV   | Standard IEC 61000-4-2 |

**Thermal Characteristics**

| Characteristic                                   | Symbol           | Value       | Unit |
|--|------------------|-------------|------|
| Package Power Dissipation (Note 5)               | P <sub>D</sub>   | 200         | mW   |
| Thermal Resistance, Junction to Ambient (Note 5) | R <sub>θJA</sub> | 625         | °C/W |
| Operating Junction Temperature Range             | T <sub>J</sub>   | -65 to +150 | °C   |
| Storage Temperature Range                        | T <sub>STG</sub> | -65 to +150 | °C   |

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

| Characteristic                   | Symbol           | Min | Typ  | Max  | Unit | Test Conditions                                       |
|----------------------------------|------------------|-----|------|------|------|---|
| Reverse Working Voltage          | V <sub>RWM</sub> | -   | -    | 5.0  | V    | -   |
| Breakdown Voltage                | V <sub>BR</sub>  | 6   | 7    | 8    | V    | I <sub>R</sub> = 1.0mA                                |
| Reverse Leakage Current (Note 6) | I <sub>R</sub>   | -   | 10   | 100  | nA   | V <sub>RWM</sub> = 5V                                 |
| Clamping Voltage (Note 4)        | V <sub>CL</sub>  | -   | 7.0  | 9.0  | V    | I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20μs         |
|                                  |                  | -   | 8.7  | 10.7 | V    | I <sub>PP</sub> = 3A, t <sub>p</sub> = 8/20μs         |
|                                  |                  | -   | 10.5 | 12.0 | V    | I <sub>PP</sub> = 5A, t <sub>p</sub> = 8/20μs         |
|                                  |                  | -   | 11.5 | 14.0 | V    | I <sub>PP</sub> = 6A, t <sub>p</sub> = 8/20μs         |
| Differential Resistance          | R <sub>DIF</sub> | -   | 0.2  | -    | Ω    | I <sub>R</sub> = 1.0A, t <sub>p</sub> = 8/20μs        |
| Channel Input Capacitance        | C <sub>T</sub>   | -   | 15   | 20   | pF   | V <sub>IN</sub> = 0 V, f = 1MHz<br>(Channel to Pin 2) |

- Notes:
4. Measured from channel to pin 2; Non-repetitive current pulse per Fig. 2.
  5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
  6. Short duration pulse test used to minimize self-heating effect.

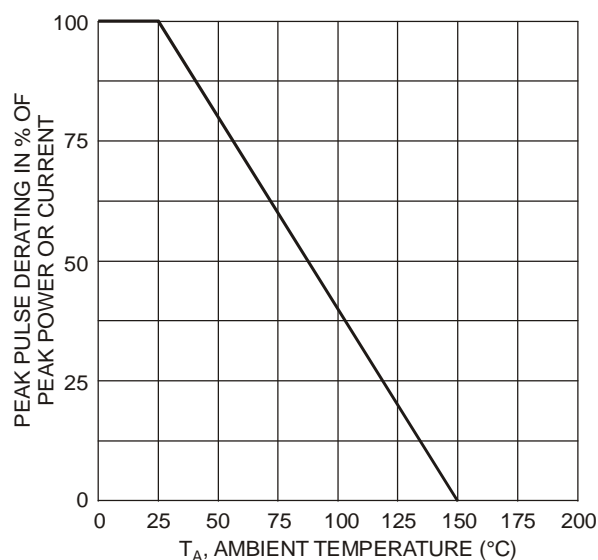


Fig. 1 Pulse Derating Curve

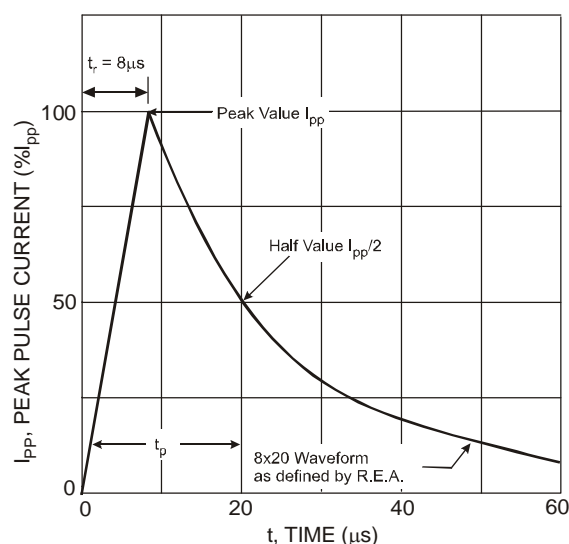


Fig. 2 Pulse Waveform

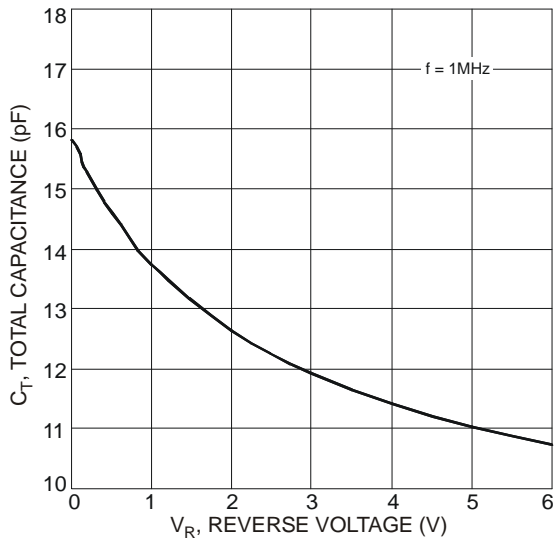


Fig. 3 Typical Total Capacitance vs. Reverse Voltage

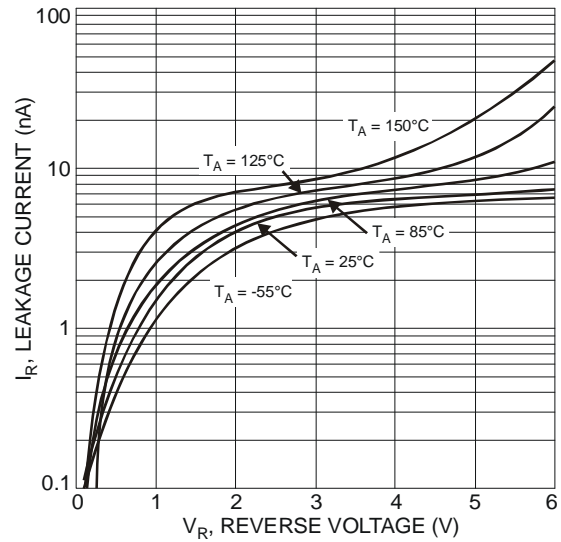
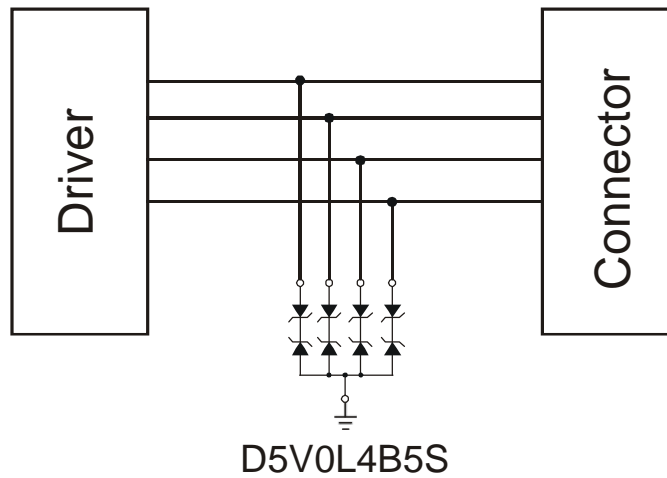
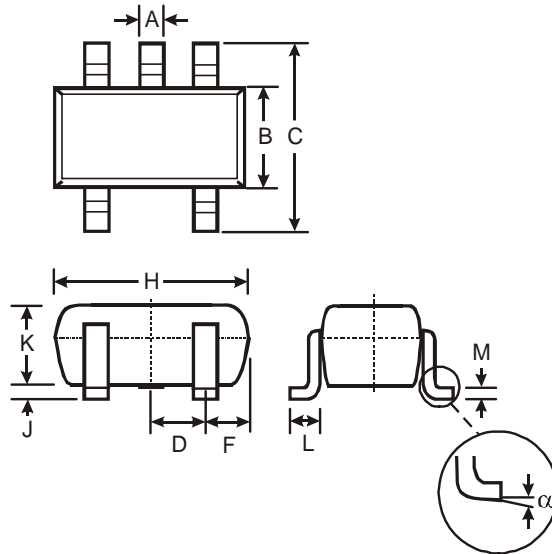


Fig. 4 Typical Reverse Characteristics

## Typical Applications

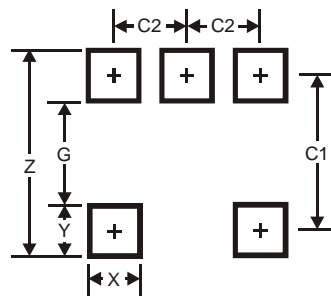


## Package Outline Dimensions



| SOT353               |          |      |
|----------------------|----------|------|
| Dim                  | Min      | Max  |
| A                    | 0.10     | 0.30 |
| B                    | 1.15     | 1.35 |
| C                    | 2.00     | 2.20 |
| D                    | 0.65 Typ |      |
| F                    | 0.40     | 0.45 |
| H                    | 1.80     | 2.20 |
| J                    | 0        | 0.10 |
| K                    | 0.90     | 1.00 |
| L                    | 0.25     | 0.40 |
| M                    | 0.10     | 0.22 |
| $\alpha$             | 0°       | 8°   |
| All Dimensions in mm |          |      |

## Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z          | 2.5           |
| G          | 1.3           |
| X          | 0.42          |
| Y          | 0.6           |
| C1         | 1.9           |
| C2         | 0.65          |

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